

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Previously Presented) A semiconductor device comprising:
a supporting substrate made of insulating material;
a conductive pattern provided on a surface of the supporting substrate;
an external connecting terminal provided on a back surface of the supporting substrate
and electrically connected to the conductive patterns;
a fuse element provided on the conductive pattern; and
a transparent glass plate that covers the fuse element and that forms a hollow airtight
portion between the supporting substrate and the transparent glass plate.
2. (Canceled)
3. (Original) A semiconductor device according to claim 1, wherein the supporting
substrate includes a flat supporting portion and a column portion, and the conductive patterns are
provided on the flat supporting portion.
4. (Previously Presented) A semiconductor device according to claim 1, wherein the
transparent glass plate is adhered onto the column portion.
5. (Currently Amended) A semiconductor device according to claim 1, wherein a via hole
is provided in the supporting substrate, and the ~~circuit~~ fuse element and the external connecting
terminals are electrically connected through the via hole.

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6. (Canceled)

7. (Previously Presented) A semiconductor device according to claim 1, wherein the fuse element is formed of a metal wire.

Claims 8 – 11 (Cancelled)